

Technical Data Sheet

Trovidur[®] EC-FR

Typical characteristics

- Clean Room Material

Typical industries

- Clean-Room Technology
- Semiconductor Industry
- Semiconductor factory equipment
- Semiconductor Front-End applications
- Semiconductor Front-End Wet Bench

	Test method	Unit	Guideline value
General properties			
Density	DIN EN ISO 1183-1	g / cm ³	~1,46
Water absorption	DIN EN ISO 62	%	0,2
Cleanroom Materials Flammability Test Protocol (Thickness 6...25 mm)	FM 4910		listed
Mechanical properties			
Yield stress	DIN EN ISO 527	MPa	50
Elongation at break	DIN EN ISO 527	%	20
Tensile modulus of elasticity	DIN EN ISO 527	MPa	3000
Notched impact strength	DIN EN ISO 179	kJ / m ²	4
Shore hardness	DIN EN ISO 868	scale D	82
Ball indentation hardness	DIN EN ISO 2039-1	MPa	115
Compressive strength	DIN EN ISO 604	MPa	75
Bending strength	DIN EN ISO 178	MPa	80
Thermal properties			
Thermal conductivity	DIN EN ISO 8302	W / (m * K)	0,16
Vicat softening temperature	DIN EN ISO 306, Vicat B	°C	75
Service Temperature		°C	-15 ... +60
Heat deflection temperature	DIN EN ISO 75	°C	70
Coefficient of linear thermal expansion	DIN EN ISO 11359-2	mm/m K	~0,075



	Test method	Unit	Guideline value
Glow wire ignition temperature	DIN EN 60695-2-13	°C	990
Glow wire flammability index	DIN EN 60695-2-12	°C	960
Electrical properties			
Dielectric constant	IEC 60250		~3,2
Dielectric dissipation factor (10 ⁶ Hz)	IEC 60250		~0,02
Volume resistivity	DIN EN 62631-3-1	Ohm * cm	>10 ¹⁵
Surface resistivity	DIN EN 62631-3-2	Ohm	>10 ¹³
Dielectric strength	IEC 60243	kV / mm	12
Comparative tracking index	IEC 60112	CTI	600

The data stated above are average values ascertained by statistical tests on a regular basis. They are in accordance with DIN EN 15860. The data above are provided purely for information and shall not be regarded as binding unless expressly agreed in a contract of sale. Information on the REACh regulation can be found in our Product Handling Information Sheets, in our REACh information letter as well as in the SCIP database.

